

AMENDMENTS TO THE CLAIMS

The following is a complete, marked up listing of revised claims with a status identifier in parentheses, underlined text indicating insertions, and strikethrough and/or double-bracketed text indicating deletions.

LISTING OF CLAIMS

Claims 1-58 (Cancelled).

59. (New) A chemical mechanical polishing (CMP) table having a monitoring function for monitoring a CMP process in-situ, the CMP table comprising:

a polishing pad including an in-situ window area that is thinner than the polishing pad adjacent to the in-situ window area; and

a platen attached to an opposite side of the polishing pad on a polishing side,

wherein the in-situ window area is composed of the same material layer as the polishing pad adjacent to the in-situ window area, and the platen has a hole which is vertically aligned with the in-situ window area.

60. (New) The CMP table according to claim 59, wherein the in-situ window area has a thickness of 1.0 to 2.0 mm.

61. (New) The CMP table according to claim 59, wherein the polishing pad is made of at least one of syndiotactic 1,2-polybutadiene, polyurethane, and PBD.

62. (New) The CMP table according to claim 59, wherein the platen has a platen window made of a transparent material in the hole of the platen to provide a void between the in-situ window area and the platen window.

63. (New) The CMP table according to claim 62, wherein the transparent material is at least one of polycarbonate, polyethylene terephthalate glycol, polypropylene, 2-aryl glycol carbonate, quartz, and glass.

64. (New) The CMP table according to claim 62, wherein the platen window is flush with the platen.

65. (New) The CMP table according to claim 62, wherein the platen window protrudes from the platen to reduce the void.

66. (New) The CMP table according to claim 62, wherein the platen window protrudes from the platen to fill the void.

67. (New) The CMP table according to claim 62, further comprising a transparent supporting layer in the void.

68. (New) The CMP table according to claim 67, wherein the platen window protrudes from the platen and the transparent supporting layer is recessed from the polishing pad.

69. (New) The CMP table according to claim 67, wherein the platen window is recessed from the platen and the transparent supporting layer protrudes from the polishing pad.

70. (New) The CMP table according to claim 67, wherein the void is filled with the transparent supporting layer.